

SPECIFICATION

ADHESIVE COMPOSITION AND JOINING METHOD UTILIZING THE
ADHESIVE COMPOSITION

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TECHNICAL FIELD

This invention relates to an adhesive composition which is flowable in ordinary state, shows a spreadable viscosity, provides temporary bonding or fixing when its cohesion is improved by short-time exposure to an active energy radiation, and reaches a final bonding power when subjected to crosslinking or polymerization, and also to a joining method utilizing the adhesive composition.

BACKGROUND ART

15 In recent years, adhesives have come into wide-spread use in the fields of architecture and building materials for their superior productivity and workability. With the development of factory-produced housing or the like, there is an increasing need for adhesives which suit high-speed
20 production of building components on assembly lines.

In Japanese Patent Laying-Open No. Sho 56-67366, an adhesive composition is proposed which contains a compound having a hydrolyzable silyl group such as an alkoxysilyl and cures in the presence of moisture or the like. This
25 adhesive composition exhibits superior impact resistance and